









The technology roadmap of the XGIS instrument for the THESEUS mission and other mission opportunities



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on behalf of the **XGIS** collaboration

























Summary

- GRBs as probes for Cosmology and MultiMessenger Astrophysics;
- THESEUS mission and the on board instruments;
- X and Gamma-ray Imager and Spectrometer (XGIS);
- Technological activities within the XGIS collaboration (Demonstration Module);
- R&D foreseen in the next future (hopefully in THESEUS M7 / Phase A);



















Gamma-Ray Bursts

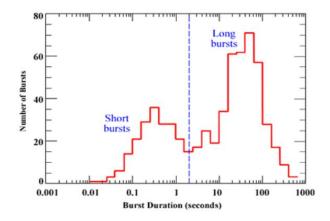
Long

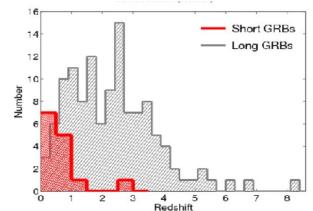
> 2 s, huge luminosities, mostly emitted in the X and gamma-rays, extending to high redshift z \sim 9, collapse of massive stars

Short

< 2 s, NS-NS or NS-BH mergers, associated with GW sources

GRBs are unique tools for Cosmology and Multimessenger Astrophysics



















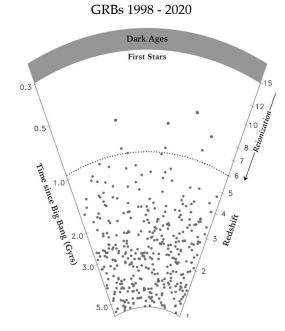




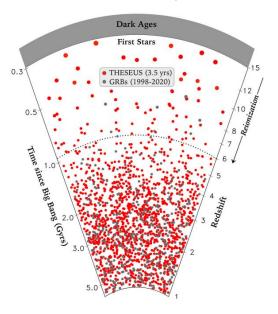
THESEUS Core Science pillars (I)

Exploit long GRBs for cosmology

- direct detection of Pop-III stars;
- star formation rate evolution;
- metallicity



GRBs THESEUS 3.5 years

















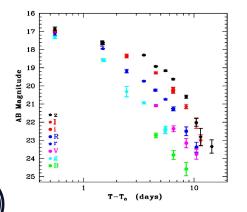


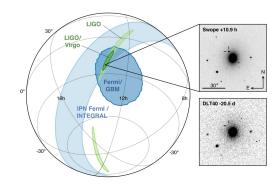


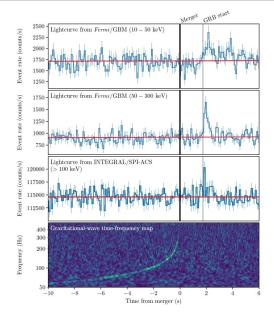
THESEUS Core Science pillars (II)

Provide fundamental contribution to Multimessenger Astrophysics

- detect short GRB associated with GW which will be routinely observed in '30s with eLISA, ET, advanced LIGO-Virgo;
- detect kilonova with arcsec localization and characterization;

























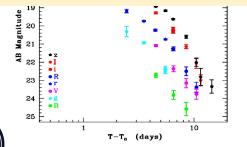
THESEUS Core Science pillars (II)

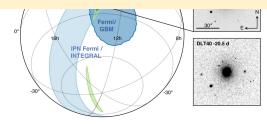
Provide fundamental contribution to **Multimessenger Astrophysics**

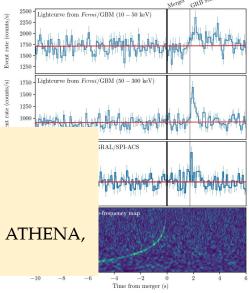
- det

eLISA THESEUS Observatory Science

- dete Contribute to the detection of new classes of high-energy transient events
 - Strong synergy with the large observatories in the '30s like SKA, CTA, ATHENA, 3-generation GW detectors







ASAPP 2023 - Advances in Space AstroParticle Physics - 2023 June 19 - 23, 2023 Perugia (Italy)

















The THESEUS instrument configuration (ESA M5 \rightarrow M7)



Soft X-ray Imager (SXI)

Two sensitive lobster-eye telescopes observing in 0.3 - 5 keV band, total FOV $\sim\!0.5$ sr source location accuracy < 2'



X-Gamma rays Imaging Spectrometer (XGIS)

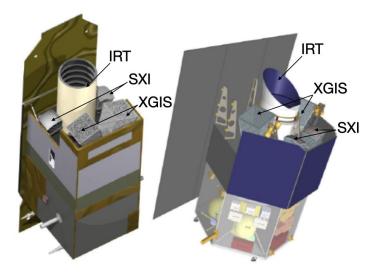
Two coded-mask X-gamma ray cameras using Silicon drift detectors coupled with CsI crystal scintillator bars observing in 2 keV – 10 MeV band, a FOV of >2 sr, overlapping the SXI <15′ GRB location accuracy



InfraRed Telescope (IRT)

A 0.7 m class IR telescope observing in the 0.7 – 1.8 µm band, providing a 15′x15′ FOV, with both imaging and moderate resolution spectroscopy capabilities arcsecond localization

M5 industrial Phase A from Airbus and Thales



Unique combination for detecting every class of GRBs





















Timeline

2018 - 2021: ESA Phase A study as M5 candidate

2022: selected for ESA Phase 0 study in M7 selection process

M7 timeline Phase A 2024 - 2025 - Launch 2037

Reference papers:

Amati et al. 2018 (Adv.Sp.Res., arXiv:1710.04638) Stratta et al. 2018 (Adv.Sp.Res., arXiv:1712.08153)

https://www.isdc.unige.ch/theseus/

Lead Proposer: Lorenzo Amati (INAF – OAS Bologna, Italy)

Coordinators: Lorenzo Amati, Paul O'Brien (Univ. Leicester, UK), Diego Gotz (CEA-Paris, France), A. Santangelo (Univ. Tuebingen, D), E. Bozzo (Univ. Genève, CH)

Payload consortium: Italy, UK, France, Germany, Switzerland, Spain, Poland, Denmark, Belgium, Czech Republic, Slovenia, Ireland, NL, ESA















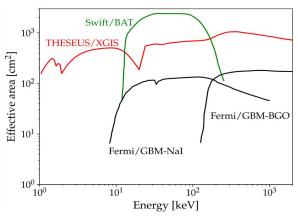


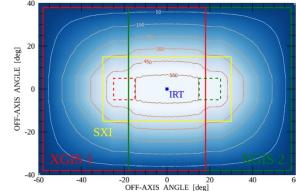


The X-Gamma Ray Imaging Spectrometer (XGIS)

Unprecedented combination of:

- Effective area (min. $>500 \text{ cm}^2$, max. $>1000 \text{ cm}^2$)
- Energy pass-band (2 keV 10 MeV)
- FoV:
 - − 2 sr with imaging capabilities < 150 keV
 - half sky < 10 MeV
- Timing $(< 5 \mu s)$















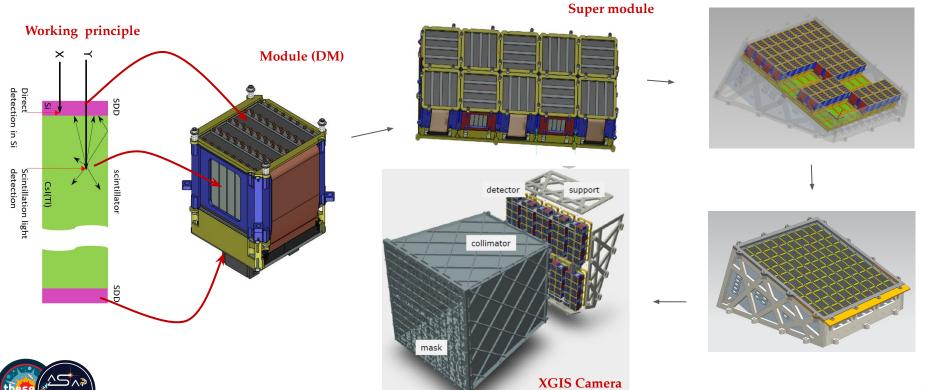








Full modularity of the architecture proposed in M5 and M7















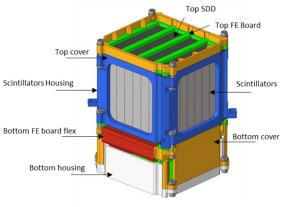




XGIS Demonstration Module (DM) overview

- Single wrapped scintillators enclosed in mechanical housing
- CsI(Tl) crystals mass 176 grams
- Readout Electronics in a single PCB with flex connections
- Clamped FE boards to preload SDD/optical couplers/scintillators
- Total mass 250 grams

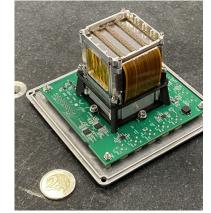




Goals of doing a DM

- implement SDDs and ASICs new technologies with CsI(Tl) scintillators
- compact design (40 mm + 5 mm pitch) to minimize XGIS Detector dead area
- SDD/scintillator optical coupling compatible with temperature range
- Robust design compatible with vibration loads













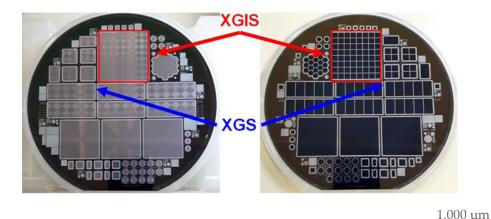


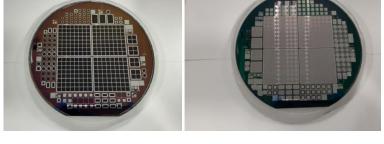






Main technologies implemented in the XGIS





ReDSoX 2019 batch with highlighted the monolithic SDD matrix (FBK Trento) designed for the XGIS instruments for THESEUS.

2020 batch implemented on XGIS DM.

Built around LYRA ASICs developed for HERMES Scientific Pathfinder:

- Politecnico di Milano (LYRA-FE)
- Università di Pavia (LYRA-BE)



670 um



LYRA-FE



LYRA-BE









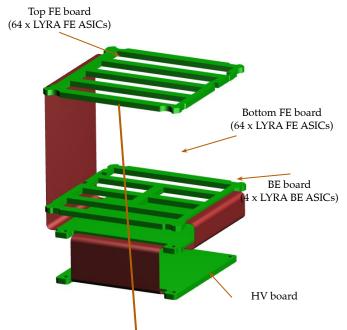








LYRA-FE ASIC: footprint and ECSS compliance



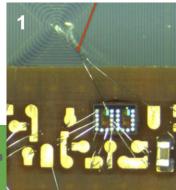
isolation between adjacent LYRA-FEs1,7 mm Chip dimension PCB edge 2,5 mm PCB edge

Very compact structure, but inspection limitations, especially for the lower SDD, which may be required after vibration or environmental tests.

1000 x 670 um Chip pad dimensions $1040 \times 710 \text{ um (chip } + 40 \text{ um)}$ Chip pad – bonding pad distance 160 um (100 um)

Pad to pad distance 160 um (100 um)

Bonding pad dimensions 160 x 200 um







































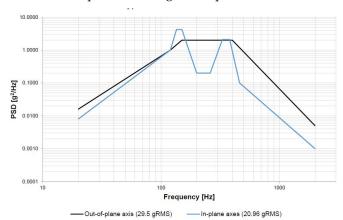




XGIS DM environmental tests

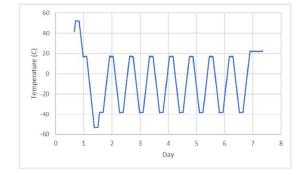
- Thermal cycling
- Random Vibrations

Dummy and DM test: Random qualification loads: 29.5 grms out-of-plane *Z*; 21.0 grms in-plane *X* and *Y*



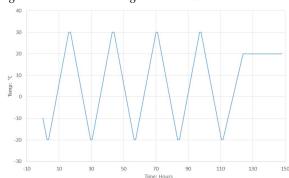
Dummy DM test:

1 cycle non-operational +50/-50 °C 7 cycles operational +15/-35 °C



DM test:

4 cycles operational +30/-20C No light output degradation observed during and after DM test















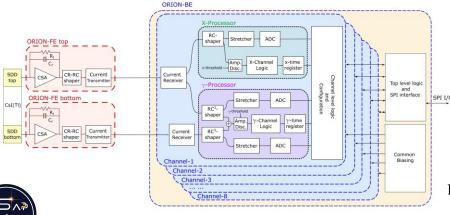






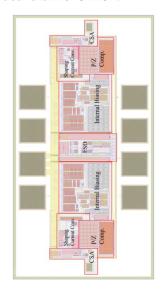
ORION ASIC - a dedicated ASIC for XGIS

- ORION-FE current geometry is similar to LYRA-FE therefore **not compliant with** ECSS rules
- Preliminary geometry (two preamplifier on the same die, back-to-back faced) which allows to design the PCB compliant to ECSS rules



Mele et al. 2020

dual channel ORION-FE



Baseline is 1 BE serving 16 FE (8 channels / 8 pixels)

















Lesson learnt – optical coupling

Transparent grid (3D printing tolerances) and separate square silicon pads.

Optical coupling between crystal and SDD needs to be improved to reduce the light output loss.

Possible improvements:

- Reflecting grid (reflecting material or reflective coating)
- Glue the grid on the SDD (on both sides like experienced on Hermes nanosat)
- Cast in place optical pads on the SDD/glued grid

top side Silicone pads on CsI crystals



bottom side Silicone pads on SDD













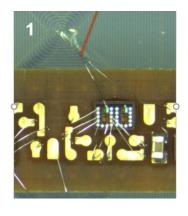


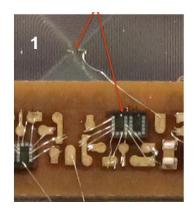






Lesson learnt – wire bonding





Weakness of wire bondings and risk to short-circuit to be mitigated

- Segmentation of the DM circuitry (Orion ASIC will serve just 8 SDDs instead of the 32 of the Lyra ASIC)
- Review handling procedure to de-risk bonding contact during integration
- Passivation of the bonded PCB with a (thin) conformal coating















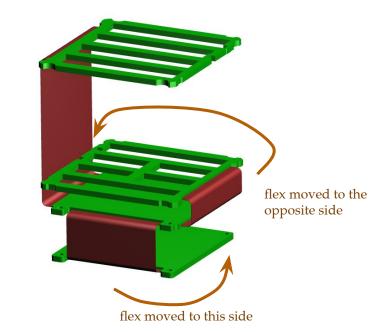




Lesson learnt – mechanical housing

Mechanical Housing design and integration procedure to be consolidated

- Review mechanical design to allow more smart inspection of both top and bottom SDDs
- Crystals/SDDs/FEs assembly housed separately by BE/HV boards to ease and to better control clamping preloads
- More robust mechanical housing and fixation points with respect to in-plane loads



















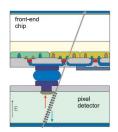


Future/potential R&D activities

- New DM with the ORION ASIC (the ASIC specifically dedicated to XGIS);
- Optimization of the mechanical mounting: different assembly of the PCBs but with the same mechanical concept;
- Investigate a faster and more reliable SDD/ASIC assembly based on the **flip-chip** ball-bonding method
- Study of a mass production process for scintillator crystals bar cutting and wrapping

























Conclusions I: THESEUS mission concept

- THESEUS is a powerful and innovative mission to fully exploit GRBs for studying the Early Universe;
- THESEUS will provide a fundamental contribution to **Multi-messenger astrophysics**;
- THESEUS was evaluated excellent for scientific, programmatic and technological aspects in Phase A of ESA M5, although it was not adopted;
- THESEUS has been assessed in Phase A of ESA M5: excellent evaluation under scientific, programmatic, technological aspects even if not adopted;
- THESEUS is now competing in M7. Downselection $6 \rightarrow 3$ mission proposals is expected in November 2023;



















Conclusions II: the XGIS instrument status

A compact XGIS 8 x 8 pixels, 5 mm pitch DM has been successfully realized. Thermal-mechanical design needs to be consolidated

Light yield is preserved during temperature cycling. Light yield can be optimized to achieve the same light output of the single scintillator bar.

Mechanical housing needs to be consolidated to get a robust design able to survive the severe launch loads. The design concept needs to be refined considering the constraints in DM dimensions and pitch size using possibly a larger number of fasteners acting with a more uniform preload.

The DM design with ORION ASIC will offer advantages in some areas of the design that can be consolidated: more reliable SDD to PCB electrical bonding connections and the possibility to perform inspection on both detector sides.



















The THESEUS instrument configuration



Soft X-ray Imager (SXI)

Two sensitive lobster-eye telescopes observing in 0.3 - 5 keV band, total FOV of ~ 0.5 sr with source location accuracy <2'



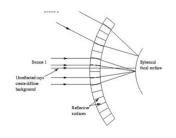
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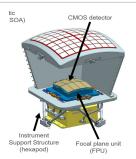
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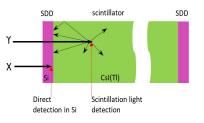


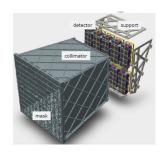
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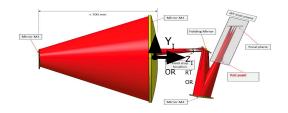
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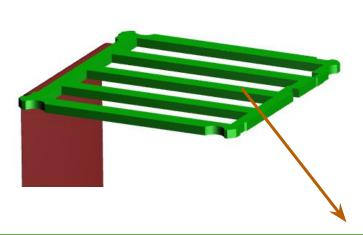


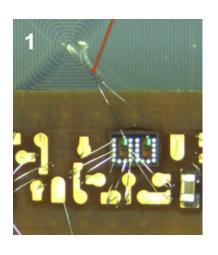






LYRA-FE ASIC: footprint and ECSS compliance

















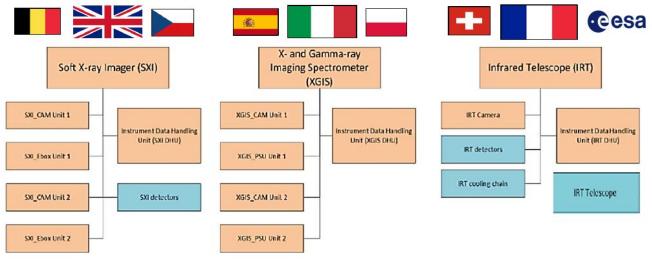


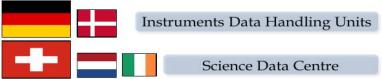






THESEUS consortium in M5







Main ground station (ASI/Malindi)











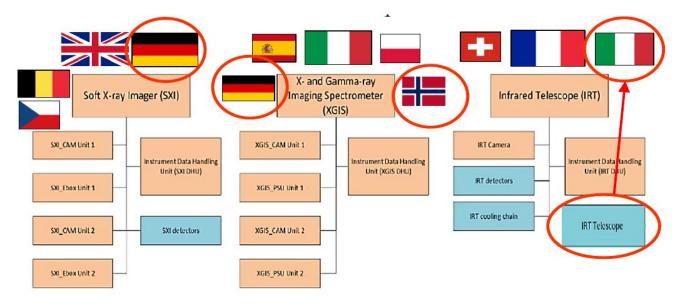


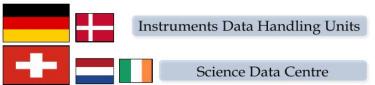






THESEUS consortium in M7







Main ground station (ASI/Malindi)

